

32-Channel Serial-to-Parallel Converter with Open-Drain Outputs

Features

- 100 mA Minimum Sink Current
- 16 MHz Shift Register Speed
- Polarity and Blanking Inputs
- CMOS-Compatible Inputs

Applications

- Inkjet and Electrostatic Print Heads
- AC-Electroluminescent Displays
- Microelectromechanical Systems (MEMS) Applications

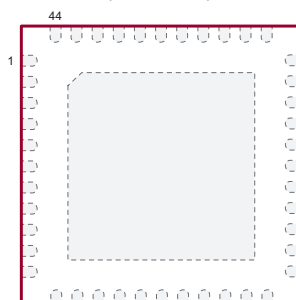
General Description

The HV5523 is a low-voltage serial to high-voltage parallel converter with open-drain outputs. This device is designed as a driver for AC electroluminescent displays. It can also be used in any application requiring multiple-output high-voltage current sinking capabilities, such as driving inkjet and electrostatic print heads, plasma panels, vacuum fluorescent and large matrix LCD displays.

This device consists of a 32-bit Shift register, 32 latches and control logic to perform the polarity selection and blanking of the outputs. Data are shifted through the Shift register on the high-to-low transition of the clock. The HV5523 shifts counter clockwise when viewed from the top of the package. A data output buffer is provided for cascading devices. This output reflects the current status of the last bit of the Shift register. Operation of the Shift register is not affected by the $\overline{LE}$ (latch enable), $\overline{BL}$ (blanking) and the $\overline{POL}$ (polarity) inputs. Transfer of data from the Shift register to the latch occurs when the $\overline{LE}$ (latch enable) input is high. The data in the latch are stored when $\overline{LE}$ is low.

Package Type

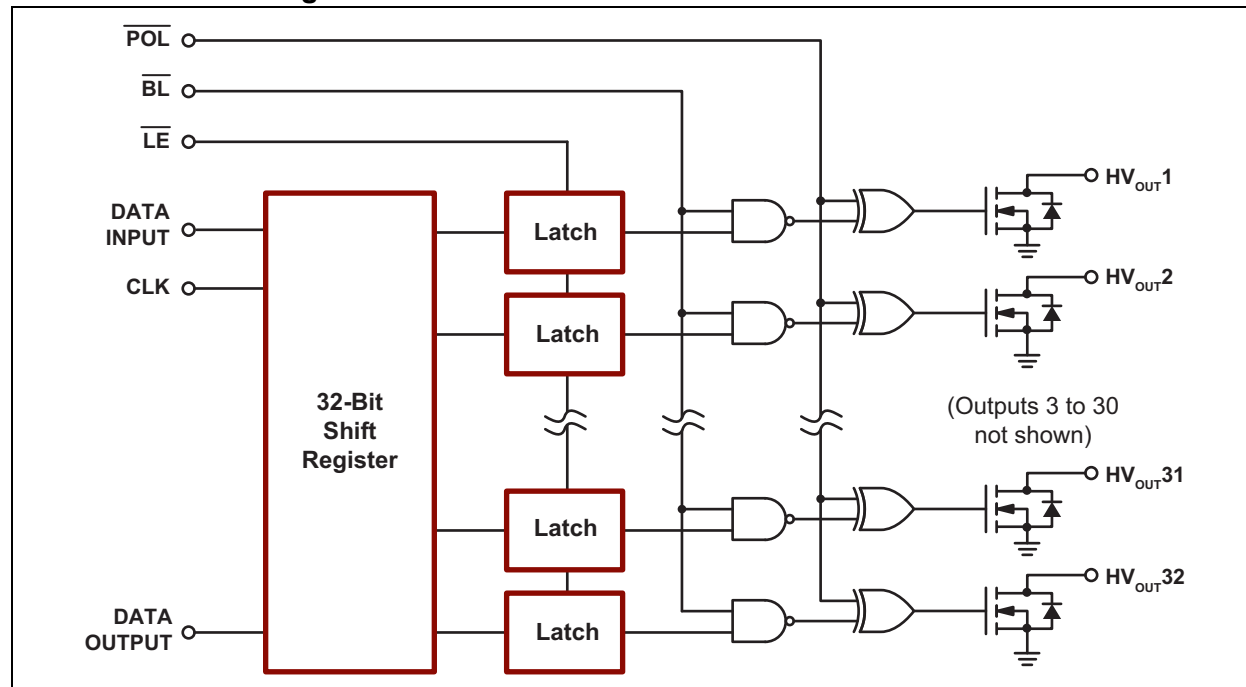
44-lead QFN
(Top view)



See [Table 2-1](#) for pin information.

HV5523

Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Supply Voltage, V_{DD} (Note 1)	-0.5V to +7V
Output Voltage, HV_{OUT} (Note 1)	-0.5V to +230V
Logic Input Levels (Note 1)	-0.5V to $V_{DD} + 0.5V$
Ground Current (Note 2)	1.5A
Maximum Junction Temperature, $T_{J(MAX)}$	+125°C
Storage Temperature, T_S	-65°C to +150°C
Continuous Total Power Dissipation:	
44-lead QFN (Note 3)	3.4W

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

- Note 1:** All voltages are referenced to V_{SS} .
Note 2: Duty cycle is limited by the total power dissipated in the package.
Note 3: 1 oz. 4-layer 3" x 4" PCB

RECOMMENDED OPERATING CONDITIONS

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Logic Supply Voltage	V_{DD}	4.5	—	5.5	V	—
High-Voltage Output	HV_{OUT}	-0.3	—	+220	V	—
High-Level Input Voltage	V_{IH}	0.8 V_{DD}	—	V_{DD}	V	—
Low-Level Input Voltage	V_{IL}	0	—	0.2 V_{DD}	V	—
Clock Frequency	f_{CLK}	—	—	16	MHz	—
Operating Ambient Temperature	T_A	-40	—	+85	°C	—

DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: with recommended operating conditions, unless otherwise noted.

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
V_{DD} Supply Current	I_{DD}	—	—	25	mA	$f_{CLK} = 16$ MHz, $f_{DATA} = 8$ MHz
Quiescent V_{DD} Supply Current	I_{DDQ}	—	—	100	μA	$D_{IN} = 0V$, all input logic pins = 0V, all outputs off
Off-State Output Current	$I_{O(OFF)}$	—	—	10	μA	All outputs high, all switches parallel
High-Level Logic Input Current	I_{IH}	—	—	1	μA	$V_{IH} = V_{DD}$
Low-Level Logic Input Current	I_{IL}	—	—	-1	μA	$V_{IL} = 0V$
High-Level Output Data Out	V_{OH}	$V_{DD} - 1V$	—	—	V	$ID_{OUT} = -10$ mA
Low-Level Output Voltage	HV_{OUT}	V_{OL}	—	15	V	$I_{HV_{OUT}} = +100$ mA
	Data Out		—	1	V	$ID_{OUT} = +10$ mA
HV_{OUT} Clamp Voltage	V_{OC}	—	—	-1.5	V	$I_{OL} = -100$ mA

AC ELECTRICAL CHARACTERISTICS

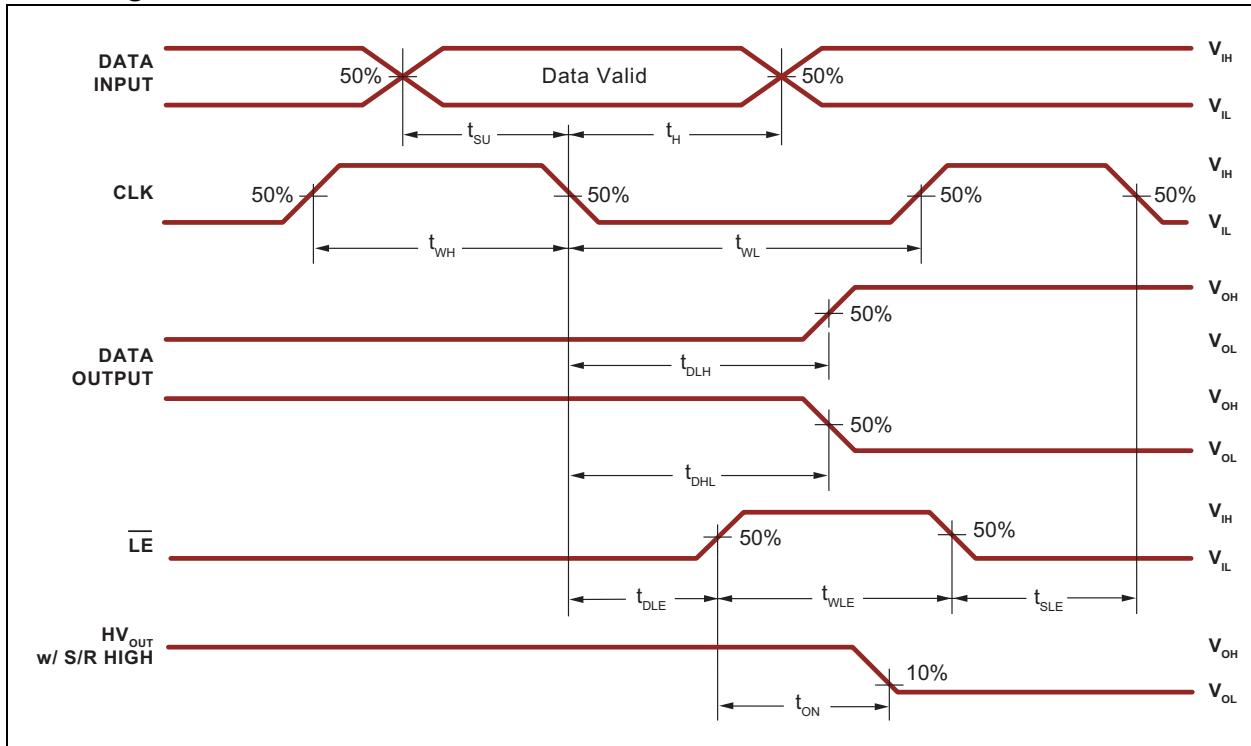
Electrical Specifications: $V_{DD} = 5V$, $T_J = 25^{\circ}C$						
Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Clock Frequency	f_{CLK}	—	—	16	MHz	—
Clock Pulse Width, High or Low	t_{WL}, t_{WH}	31	—	—	ns	—
Data Setup Time before CLK Falls	t_{SU}	25	—	—	ns	—
Data Hold Time after CLK Falls	t_H	10	—	—	ns	—
Turn-On Time, HV_{OUT} from Enable	t_{ON}	—	—	400	ns	$R_L = 2\text{ k}\Omega$ to V_{PP} maximum
Delay Time Clock to Data High to Low	t_{DHL}	—	—	35	ns	$C_L = 15\text{ pF}$
Delay Time Clock to Data Low to High	t_{DLH}	—	—	35	ns	$C_L = 15\text{ pF}$
Delay Time Clock to $\overline{LE}$ Low to High	t_{DLE}	20	—	—	ns	—
Width of $\overline{LE}$ Pulse	t_{WLE}	20	—	—	ns	—
$\overline{LE}$ Setup Time Before Clock Falls	t_{SLE}	20	—	—	ns	—
Digital Logic Input Capacitance	C_{IN}	—	—	15	pF	—

TEMPERATURE SPECIFICATIONS

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Ambient Temperature	T_A	-40	—	+85	$^{\circ}C$	—
Maximum Junction Temperature	$T_{J(MAX)}$	—	—	+125	$^{\circ}C$	—
Storage Temperature	T_S	-65	—	+150	$^{\circ}C$	—
PACKAGE THERMAL RESISTANCE						
44-lead QFN	θ_{JA}	—	19	—	$^{\circ}C/W$	Note 1

Note 1: 1 oz. 4-layer 3" x 4" PCB

Switching Waveforms



2.0 PIN DESCRIPTION

The details on the pins of HV5523 are listed in [Table 2-1](#). Refer to [Package Type](#) for the location of pins.

TABLE 2-1: 44-LEAD QFN PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	HV _{OUT} 11	High-voltage output
2	HV _{OUT} 12	High-voltage output
3	HV _{OUT} 13	High-voltage output
4	HV _{OUT} 14	High-voltage output
5	HV _{OUT} 15	High-voltage output
6	HV _{OUT} 16	High-voltage output
7	HV _{OUT} 17	High-voltage output
8	HV _{OUT} 18	High-voltage output
9	HV _{OUT} 19	High-voltage output
10	HV _{OUT} 20	High-voltage output
11	HV _{OUT} 21	High-voltage output
12	HV _{OUT} 22	High-voltage output
13	HV _{OUT} 23	High-voltage output
14	HV _{OUT} 24	High-voltage output
15	HV _{OUT} 25	High-voltage output
16	HV _{OUT} 26	High-voltage output
17	HV _{OUT} 27	High-voltage output
18	HV _{OUT} 28	High-voltage output
19	HV _{OUT} 29	High-voltage output
20	HV _{OUT} 30	High-voltage output
21	HV _{OUT} 31	High-voltage output
22	HV _{OUT} 32	High-voltage output
23	DATA OUT	Data output pin
24	NC	No internal connection
25	NC	No internal connection
26	NC	No internal connection
27	POL	Inverts the polarity of the HV _{OUT} pins.
28	CLK	Clock pin. The Shift registers shift data on the falling edge of input clock.
29	VSS	Reference voltage, usually ground
30	VDD	Logic supply voltage
31	LE	Latch enable pin. Data are shifted from the Shift register to the latches on logic input high.
32	DATA IN	Data input pin

TABLE 2-1: 44-LEAD QFN PIN FUNCTION TABLE (CONTINUED)

Pin Number	Pin Name	Description
33	$\overline{\text{BL}}$	Blanking pin sets all HV _{OUT} pins ON or OFF, depending upon the state of polarity. See Table 3-2 .
34	N/C	No internal connection
35	HV _{OUT1}	High-voltage output
36	HV _{OUT2}	High-voltage output
37	HV _{OUT3}	High-voltage output
38	HV _{OUT4}	High-voltage output
39	HV _{OUT5}	High-voltage output
40	HV _{OUT6}	High-voltage output
41	HV _{OUT7}	High-voltage output
42	HV _{OUT8}	High-voltage output
43	HV _{OUT9}	High-voltage output
44	HV _{OUT10}	High-voltage output
Center Tab		Connect to VSS.

3.0 FUNCTIONAL DESCRIPTION

Follow the steps in Table 3-1 to power up and power down the HV5523.

TABLE 3-1: POWER-UP AND POWER-DOWN SEQUENCE

Power-Up		Power-Down	
Step	Description	Step	Description
1	Connect ground.	1	Remove all inputs.
2	Apply V _{DD} .	2	Remove V _{DD} .
3	Set all inputs to a known state.	3	Disconnect ground.

TABLE 3-2: FUNCTION TABLE

Function	Inputs ⁽¹⁾					Outputs				
	Data	CLK	$\overline{\text{LE}}$	$\overline{\text{BL}}$	$\overline{\text{POL}}$	Shift Register		High-Voltage Output		Data Out
						1	2...32	1	2...32	
All On	X	X	X	L	L	Note 2	Note 2	On	On	Note 2
All Off	X	X	X	L	H	Note 2	Note 2	Off	Off	Note 2
Invert Mode	X	X	L	H	L	Note 2	Note 2	Note 2	Note 2	Note 2
Load S/R	H or L	↓	L	H	H	H or L	Note 2	Note 2	Note 2	Note 2
Load Latches	X	H or L	↑	H	H	Note 2	Note 2	Note 2	Note 2	Note 2
	X	H or L	↑	H	L	Note 2	Note 2	Note 2	Note 2	Note 2
Transparent Latch Mode	L	↓	H	H	H	L	Note 2	Off	Note 2	Note 2
	H	↓	H	H	H	H	Note 2	On	Note 2	Note 2

Note 1: H = High logic level
L = Low logic level
X = Don't care
↓ = Hight-to-low transition
↑ = Low-to-high transition

2: Dependent on previous stage's state before the last CLK ↓ or last $\overline{\text{LE}}$ high.

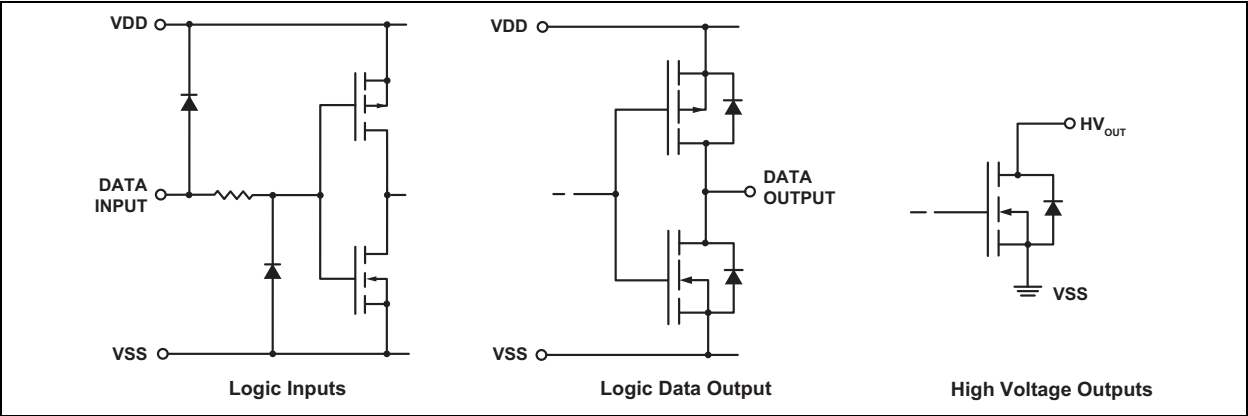
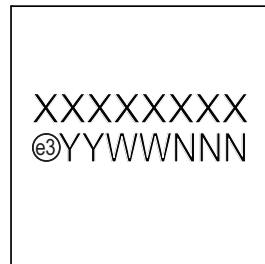


FIGURE 3-1: Input and Output Equivalent Circuits.

4.0 PACKAGE MARKING INFORMATION

4.1 Packaging Information

44-lead QFN



Example

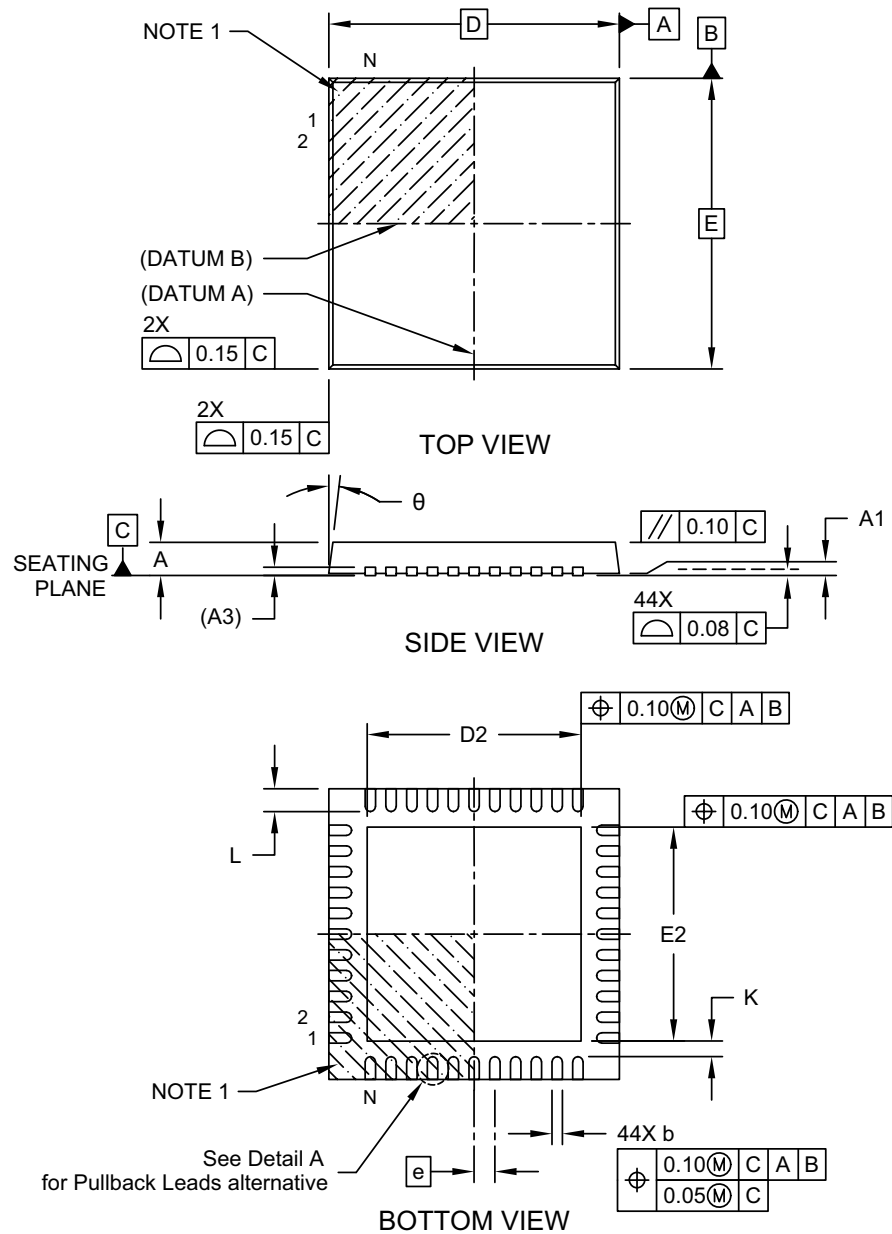


Legend:	XX...X	Product Code or Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

44-Lead Very, Very Thin Plastic Quad Flat, No Lead Package (7P) - 7x7 mm Body [WQFN]; Supertex Legacy Package K7

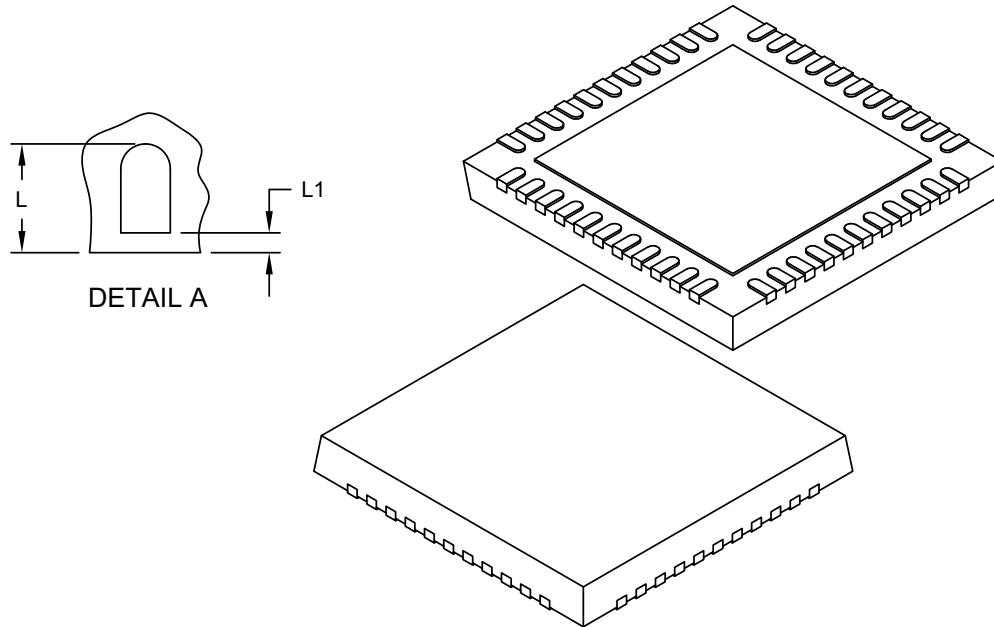
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-307A Sheet 1 of 2

44-Lead Very, Very Thin Plastic Quad Flat, No Lead Package (7P) - 7x7 mm Body [WQFN]; Supertex Legacy Package K7

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Terminals	N	44		
Pitch	e	0.50 BSC		
Overall Height	A	0.70	0.75	0.80
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.20 REF		
Overall Length	D	7.00 BSC		
Exposed Pad Length	D2	5.00	5.15	5.25
Overall Width	E	7.00 BSC		
Exposed Pad Width	E2	5.00	5.15	5.25
Terminal Width	b	0.18	0.25	0.30
Terminal Length	L	0.45	0.55	0.65
Pullback	L1	-	-	0.15
Mold Angle	θ	0°	7°	14°
Terminal-to-Exposed-Pad	K	0.20	-	-

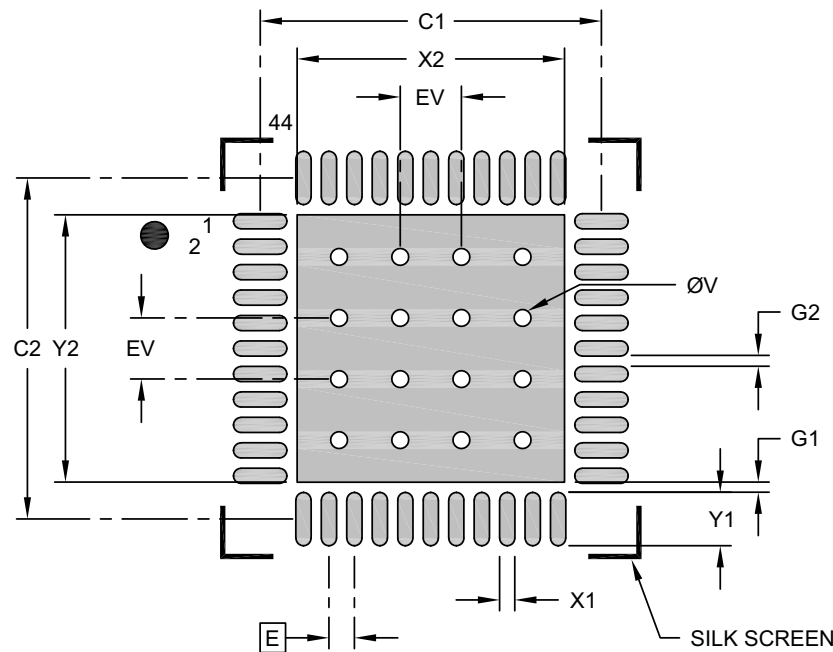
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-307A Sheet 2 of 2

44-Lead Very, Very Thin Plastic Quad Flat, No Lead Package (7P) - 7x7 mm Body [WQFN]; Supertex Legacy Package

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2			5.25
Optional Center Pad Length	Y2			5.25
Contact Pad Spacing	C1		6.70	
Contact Pad Spacing	C2		6.70	
Contact Pad Width (X44)	X1			0.30
Contact Pad Length (X44)	Y1			1.05
Contact Pad to Center Pad (X44)	G1	0.20		
Contact Pad to Contact Pad (X44)	G2	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2307A

APPENDIX A: REVISION HISTORY

Revision B (June 2025)

- Added “Obsolete Device” label to the first page.
- Updated Package Drawing to Microchip’s standard format.

Revision A (July 2019)

- Converted Supertex Doc# DSFP-HV5523 to Microchip DS20005700A
- Changed the quantity of the 44-lead QFN K7 package from 280/Tray to 260/Tray
- Changed the quantity of the 44-lead QFN K7 M933 media type from 2000/Reel to 3000/Reel
- Made minor text changes throughout the document

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

<u>PART NO.</u>	<u>XX</u>	-	<u>X</u>	-	<u>X</u>
Device	Package Options		Environmental		Media Type
Device:	HV5523	=	32-Channel Serial-to-Parallel Converter with Open-Drain Outputs		
Package:	K7	=	44-lead (7x7) WQFN		
Environmental:	G	=	Lead (Pb)-free/RoHS-compliant Package		
Media Type:	(blank)	=	260/Tray for a K7 Package		
	M933	=	3000/Reel for a K7 Package		

Examples:

a) HV5523K7-G: 32-Channel Serial-to-Parallel Converter with Open-Drain Outputs, 44-lead (7x7) WQFN, 260/Tray

b) HV5523K7-G-M933: 32-Channel Serial-to-Parallel Converter with Open-Drain Outputs, 44-lead (7x7) WQFN, 3000/Reel

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ISBN: 979-8-3371-1237-4

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